

SILICA PARTICLES, PROCESS FOR PRODUCTION OF SAME, AND RESIN
COMPOSITION CONTAINING SAME

ABSTRACT

The object of the present disclosure is to obtain silica particles having the sharp particle size distribution and low water-absorbing rate and being used suitably as a filler of a sealing resin composition, a method for producing it, and a resin composition containing the silica particles and a resin.

Silica particle having a water-absorbing rate of less than 1.0 % measured 500 hours after being kept at a temperature of 50°C and at a humidity of 90 %, and at a temperature of 85°C and at a humidity of 85 %, D90/D10 of 3 or less, a true specific gravity of 2.1 g/cm³ or more, and an average particle diameter of 10 μm or less.